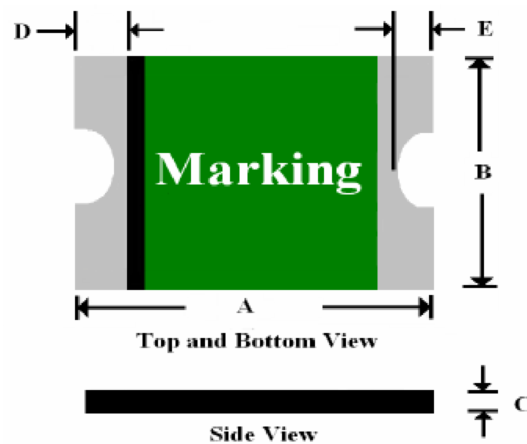
1 SCOPE

This specification defines the technical requirements of resettable fuse FSMD2920-300/24, which is according to RoHS Compliant.

2 DIMENSIONS(mm)



Model	A		B		C		D		E	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
FSMD2920-300/24	6.73	7.98	4.80	5.44	0.30	0.90	0.50	1.20	0.50	0.90

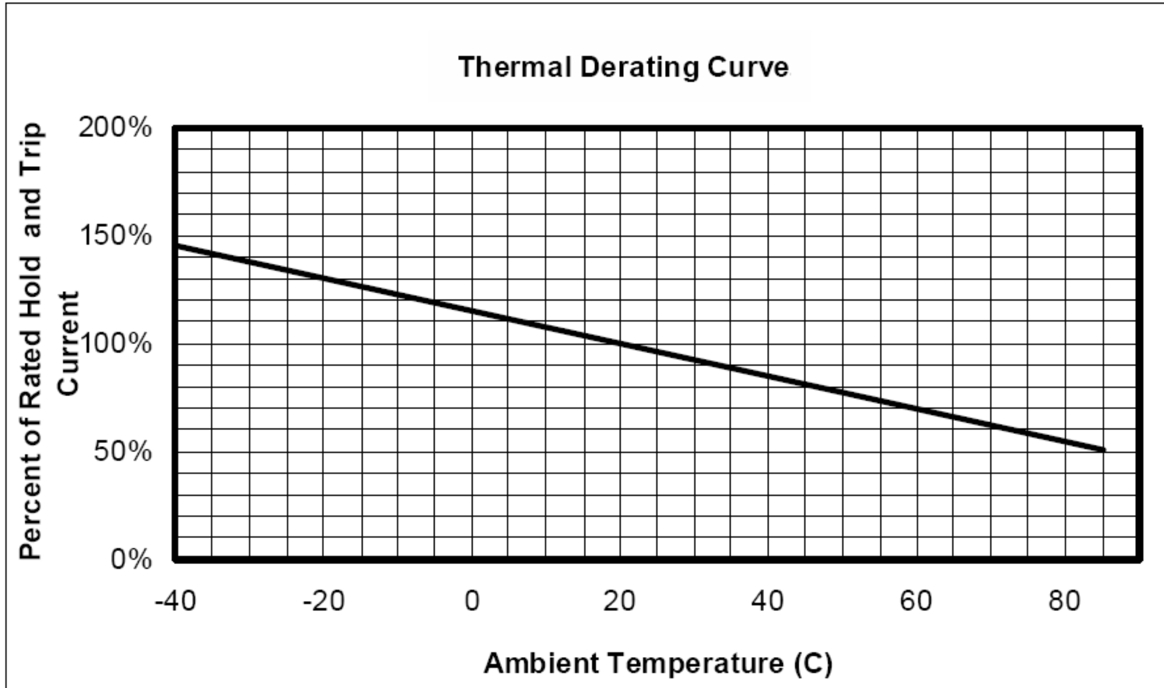
3 ELECTRICAL CHARACTERISTICS

3.1 Testing environmental temperature: 25±2℃.

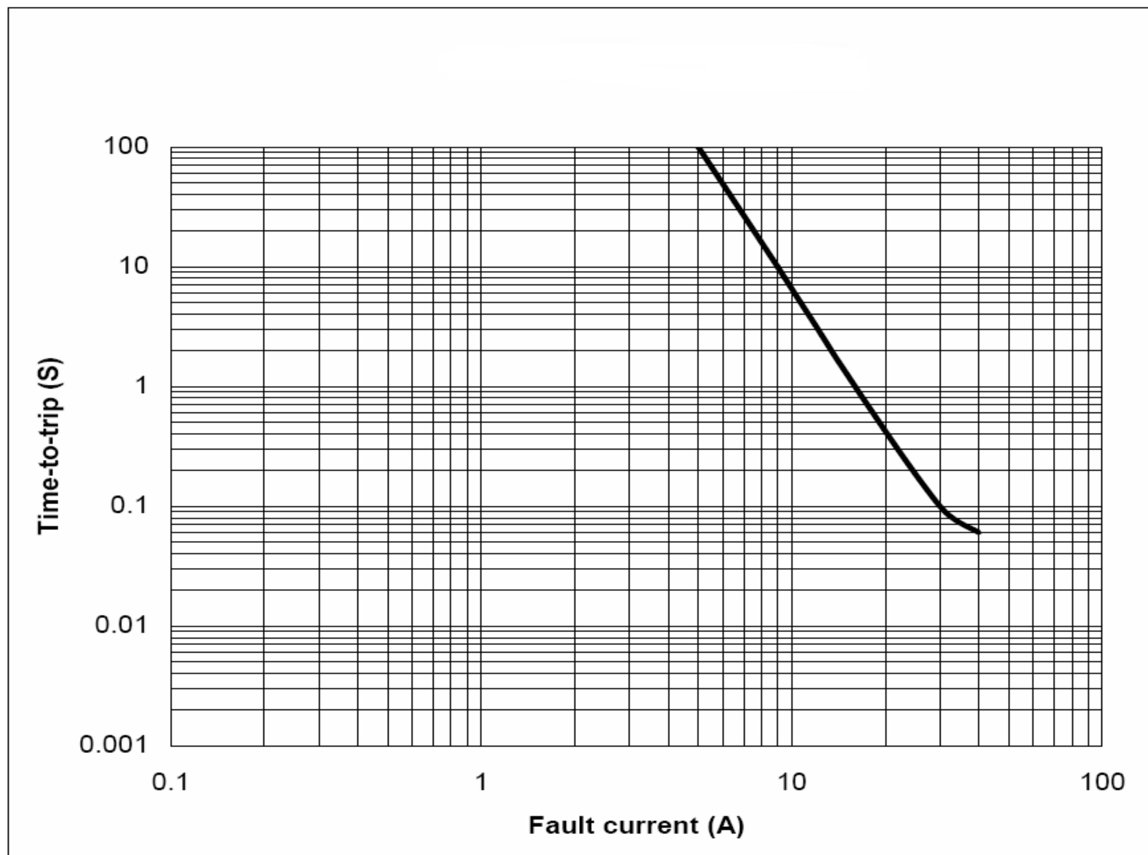
3.2 Electrical characteristics

Model	V_{Rated} (Vdc)	$I_{Max.}$ (A)	I_{hold} 25℃ (A)	I_{trip} 25℃ (A)	P_d TYP. (w)	Maximum Time To Trip		Resistance	
						Current (A)	Time (Sec)	R_{min} (Ω)	$R1_{max}$ (Ω)
FSMD2920-300/24	24	40	3.00	5.20	1.5	8.00	25.00	0.010	0.065

3.3 Thermal Derating Curve



3.4 Typical Time-To-Trip Curve at 23 ℃



4 MATERIAL SPECIFICATION

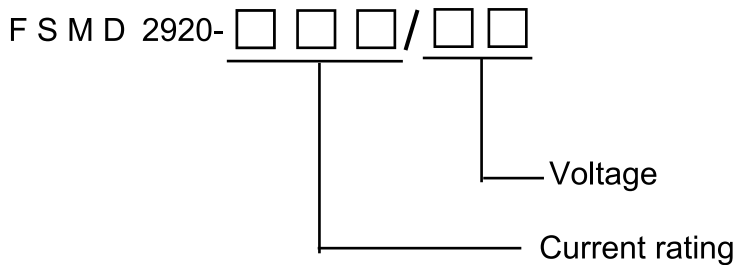
4.1 Terminal pad material: Pure Tin

4.2 EIA specification RS 186-9E, ANSI/J-std-002 Category 3

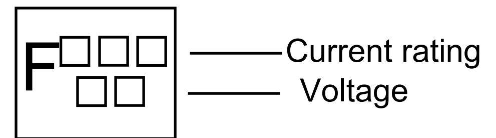
Soldering characteristics: Meets EIA specification RS 186-9E, ANSI/J-std-002 Category3

5 PART NUMBERING AND MARKING SYSTEM

Part Numbering System

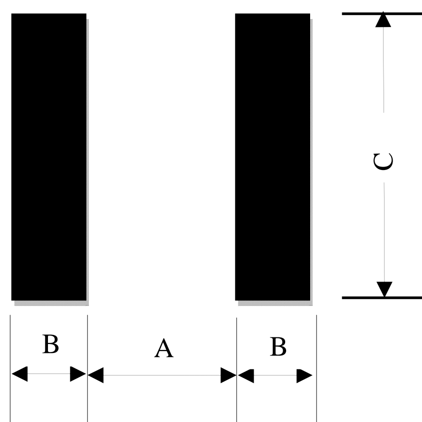


Part Marking System



6 PAD LAYOUTS、SOLDER REFLOW AND REWORK RECOMMENDATIONS

The dimension in the table below provide the recommended pad layout for each FSMD2920 device

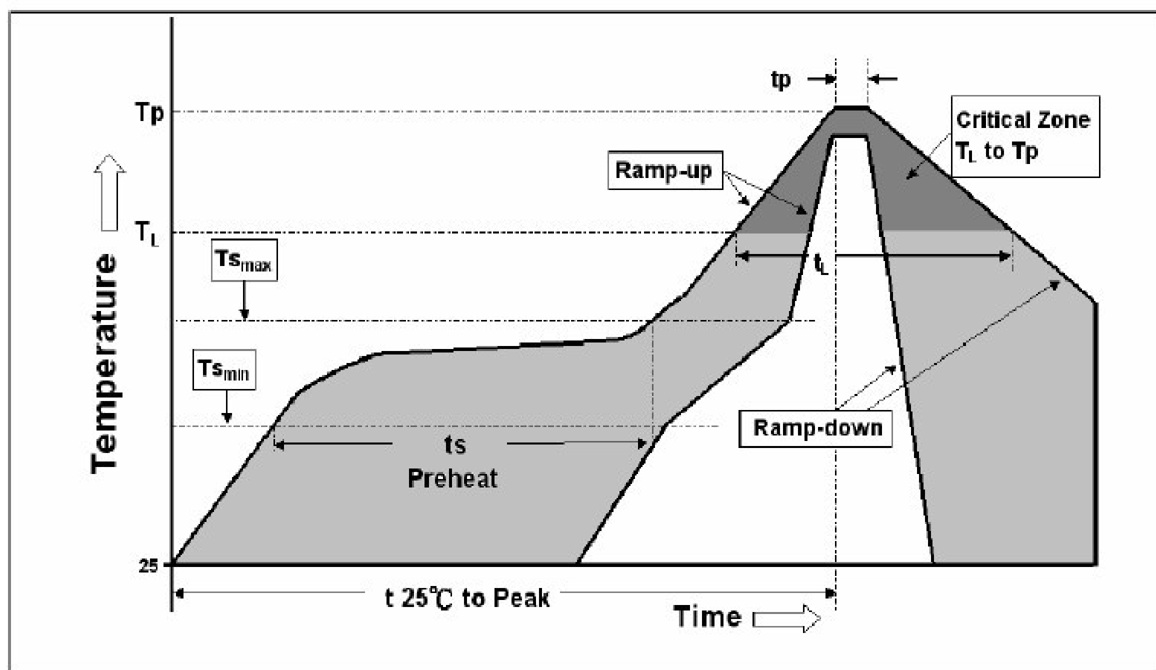


Pad dimension (millimeters)			
Device	A Nominal	B Nominal	C Nominal
FSMD2920-300/24	5.10	2.30	5.60

Profile Feature	Pb-Free Assemblely
Average Ramp-Up Rate(Tsmax to Tp)	3℃/second max
Preheat: Temperature Min (Tsmin) Temperature Max (Tsmax) Time (tsmin to tsmax)	 150℃ 200℃ 60-180seconds
Time maintained above: Temperature(T_L) Time(t_L)	 217℃ 60-150 seconds
Peak/classification Temperature (Tp)	260℃
Time within 5℃ of actual Peak: Temperature (tp)	 20-40 seconds
Ramp-Down Rate:	6℃/second max
Time 25℃to peak Temperature:	8minutes max

Note: All temperatures refer to of the package, measured on the package body surface.

Reflow Profile



Remarks：

1. Due to “Lead Free” nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.
2. If reflow temperatures exceed the recommended profile, devices may be damaged and not meet the performance requirements.
3. Devices are not designed to be wave soldered to the bottom side of the board.
4. Recommended max past thickness >0.25mm.
5. Devices can be cleaned using standard methods and aqueous solvent.
6. Rework use standard industry practices.
7. Storage Environment: Temperature< 30℃/RH < 60%.